

## PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT2718359

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY LIMITED	12/18/2013
RECEIVING PARTY DATA	
Name:	TSMC CHINA COMPANY LIMITED
Street Address:	4000, WEN XIANG RD., SONGJIANG
City:	SHANGHAI
State/Country:	CHINA
Postal Code:	201616
PROPERTY NUMBERS Total: 10	
Property Type	Number
Patent Number:	5895244
Patent Number:	5899741
Patent Number:	6025273
Patent Number:	6030732
Patent Number:	6057186
Patent Number:	6090674
Patent Number:	6130013
Patent Number:	5929509
Patent Number:	5932929
Patent Number:	6033969
CORRESPONDENCE DATA	
Fax Number:	(404)521-4286
Phone:	678-483-8899
Email:	dan.mcclure@mqlaw.com
<i>Correspondence will be sent via US Mail when the email attempt is unsuccessful.</i>	

Correspondent Name:	MCCLURE, QUALEY & RODACK, LLP
Address Line 1:	400 INTERSTATE NORTH PARKWAY SE
Address Line 2:	SUITE 200
Address Line 4:	ATLANTA, GEORGIA 30339

ATTORNEY DOCKET NUMBER:	252011-9010
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NAME OF SUBMITTER:	DANIEL R. MCCLURE
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Signature:	/Daniel R. McClure/
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Date:	02/07/2014
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Total Attachments: 3  
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**EXHIBIT B**

**PATENT ASSIGNMENT**

THIS ASSIGNMENT (the "Assignment"), effective as of December 18, 2013 is made by and between by and between TSMC China Company Limited, a People's Republic of China corporation ("Assignee"), and Taiwan Semiconductor Manufacturing Company Limited, a Taiwan, Republic of China corporation (the "Assignor"). Assignee and Assignor are referred to herein as the "Parties" and each individually as a "Party."

**WITNESSETH:**

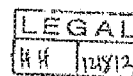
WHEREAS, the Parties entered into that certain Asset Purchase Agreement, dated as of December 18, 2013, by and among, Assignor and Assignee (the "Purchase Agreement");

WHEREAS, pursuant to the Purchase Agreement, Assignor agreed to transfer to Assignee all of the rights, title and interest of Assignor in and to certain assets, properties, rights and interests, including without limitation, certain Patent Rights (as defined in the Purchase Agreement);

WHEREAS, Assignee is desirous of acquiring (and Assignor is desirous of assigning to Assignee) the entire rights, title and interest in and to the Patent Rights and the inventions disclosed and/or claimed in the Patent Rights, and in and to any and all Letters Patents worldwide which may be obtained therefor;

NOW, THEREFORE, for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged:

1. Assignor does hereby sell, assign, transfer, and convey to Assignee to the maximum extent provided under law, all of Assignor's entire worldwide rights, title and interest in, to, and under the Patent Rights, the same to be held and enjoyed by Assignee for its own use and enjoyment and the use and enjoyment of its successors, assigns or other legal representatives, as fully and entirely as the same would have been held and enjoyed by Assignor if this assignment and sale had not been made, as assignee of its entire rights, title and interest therein and in and to all income, royalties, damages and payments now or hereafter due or payable with respect thereto in and to all causes of action (either in law or in equity) and the rights to sue, counterclaim, and recover for past, present and future infringement of the rights assigned or to be assigned under this Assignment.
2. Assignor hereby covenants and agrees that Assignor will not execute any writing or do any act whatsoever conflicting with this Assignment, and that Assignor will, at any time upon request, without further or additional consideration but at the expense of Assignee, execute such additional assignments and other writings and do such additional acts as Assignee may deem necessary or desirable to perfect Assignee's enjoyment of this grant, and render all necessary or desirable assistance in making application for and obtaining original, divisional, continuations, continuation-in-part, reexamined, reissued, or extended letters

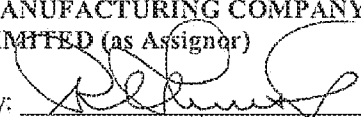


patent or of any and all foreign countries on said inventions, and in enforcing any rights or causes of action accruing as a result of such applications or patents, by giving testimony in any proceedings or transactions involving such applications or patents, and/or by executing preliminary statements and other affidavits.

3. The Parties authorize and request that the Commissioner of Patents and Trademarks of the United States, and the corresponding entities or agencies in any applicable foreign countries, record Assignee as the owner of record for the Patent Rights and issue the patent for the pending Patent Rights to the Assignee upon issuance.
4. All disputes, claims or controversies arising out of this Assignment, or the negotiation, validity or performance of this Assignment, or the transactions contemplated hereby shall be governed by and construed in accordance with the laws of the Republic of China without regard to its rules of conflict of laws.
5. This Assignment shall be binding upon and inure to the benefit of the Parties and their respective successors and assigns.
6. If any provision of this Assignment or the application of any such provision to any person or circumstance shall be held invalid, illegal or unenforceable in any respect by a court of competent jurisdiction, such invalidity, illegality or unenforceability shall not affect any other provision hereof.
7. This Assignment may be executed in two (2) counterparts, each of which when so executed and delivered shall be deemed an original, and such counterparts together shall constitute one and the same instrument.

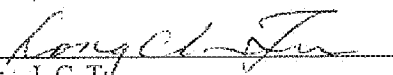
IN WITNESS WHEREOF, Assignor and Assignee have caused this Assignment to be duly executed in duplicate originals by their duly authorized representative as of the day and year first above written.

TAIWAN SEMICONDUCTOR  
MANUFACTURING COMPANY  
LIMITED (as Assignor)

By:   
Name: Richard L. Thurston  
Title: Senior Vice President and General  
Counsel



TSMC China Company Limited (as  
Assignee)

By:   
Name: L.C. Tu  
Title: President

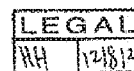


Exhibit A

Patent Rights

Patent No.	US Issued Date	US Filing Date	Expiration Date	US Patent Title
5895244	04/20/1999	01/08/1998	01/07/2018	Process to fabricate ultra-short channel NMOSFETs with self-aligned contact
5899741	05/04/1999	03/18/1998	03/17/2018	Method of manufacturing low resistance and low junction leakage contact.
6025273	02/15/2000	04/06/1998	04/05/2018	Method for etching reliable small contact holes with improved profiles for semiconductor integrated circuits using a carbon doped hard mask
6030732	02/29/2000	01/07/1999	01/06/2019	In-situ etch process control monitor.
6057186	05/02/2000	07/31/1998	07/30/2018	Method to improve butted contact resistance of an SRAM by double Vee implantation
6090674	07/18/2000	11/09/1998	11/08/2018	Method of forming a hole in the sub quarter micron range
6130013	10/10/2000	05/24/1999	05/23/2019	Birefringent interlayer for attenuating standing wave photoexposure of a photoresist layer formed over a reflective layer
5929509	07/27/1999	12/04/1997	12/03/2017	Wafer edge seal ring structure
5932929	08/03/1999	10/06/1997	10/05/2017	Tungsten tunnel-free process
6033969	03/07/2000	09/30/1996	09/29/2016	Method of forming a shallow trench isolation that has rounded and protected corners

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